

Surface Mount Superfast Recovery Rectifier
Forward Current – 1 A
FEATURES

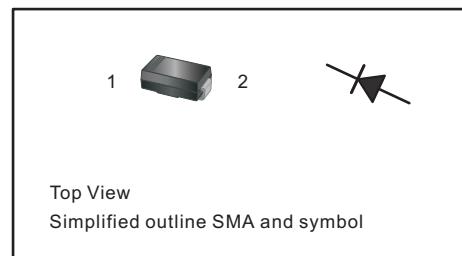
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.055g / 0.002oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

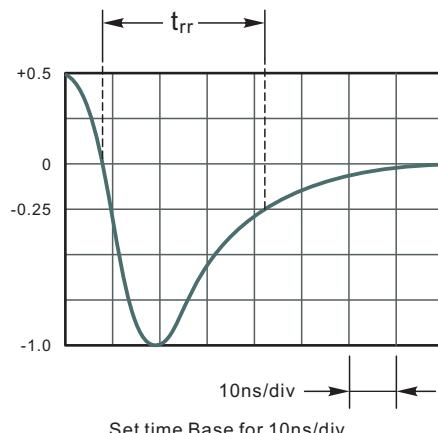
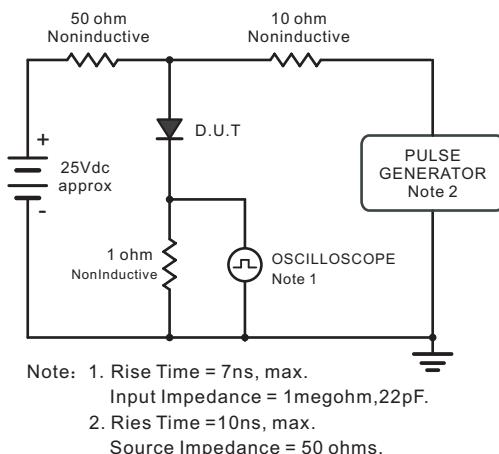
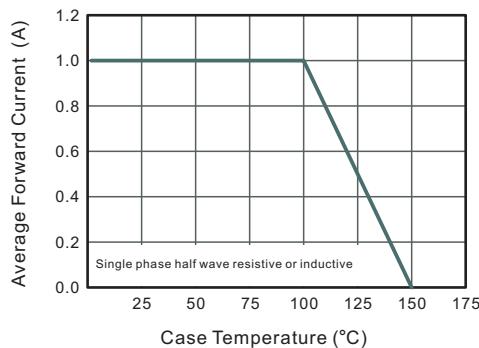
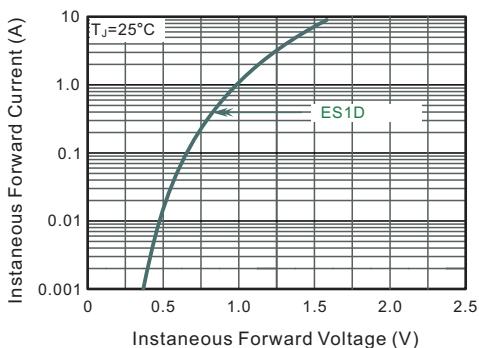
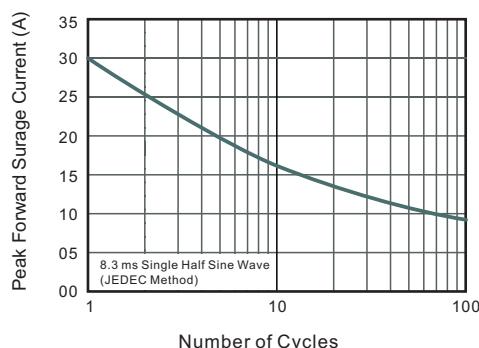
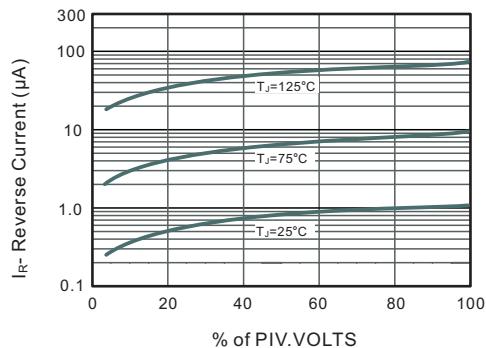
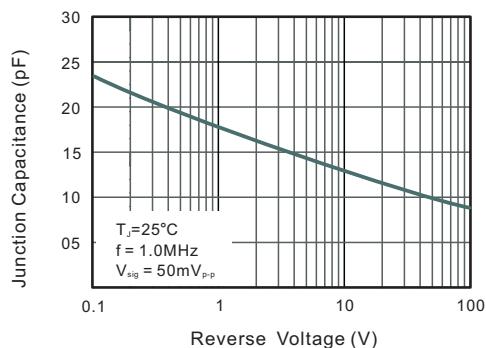

Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Parameter	Symbols	ES1D	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	200	V
Maximum RMS voltage	V _{RMS}	140	V
Maximum DC Blocking Voltage	V _{DC}	200	V
Maximum Average Forward Rectified Current at T _L = 100 °C	I _{F(AV)}	1	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	30	A
Maximum Forward Voltage at 1 A	V _F	1	V
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I _R	5 100	µA
Typical Junction Capacitance at V _R =4V, f=1MHz	C _j	15	pF
Maximum Reverse Recovery Time ⁽¹⁾	t _{rr}	35	ns
Typical Thermal Resistance ⁽²⁾	R _{θJA}	110	°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150	°C

(1) Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A.

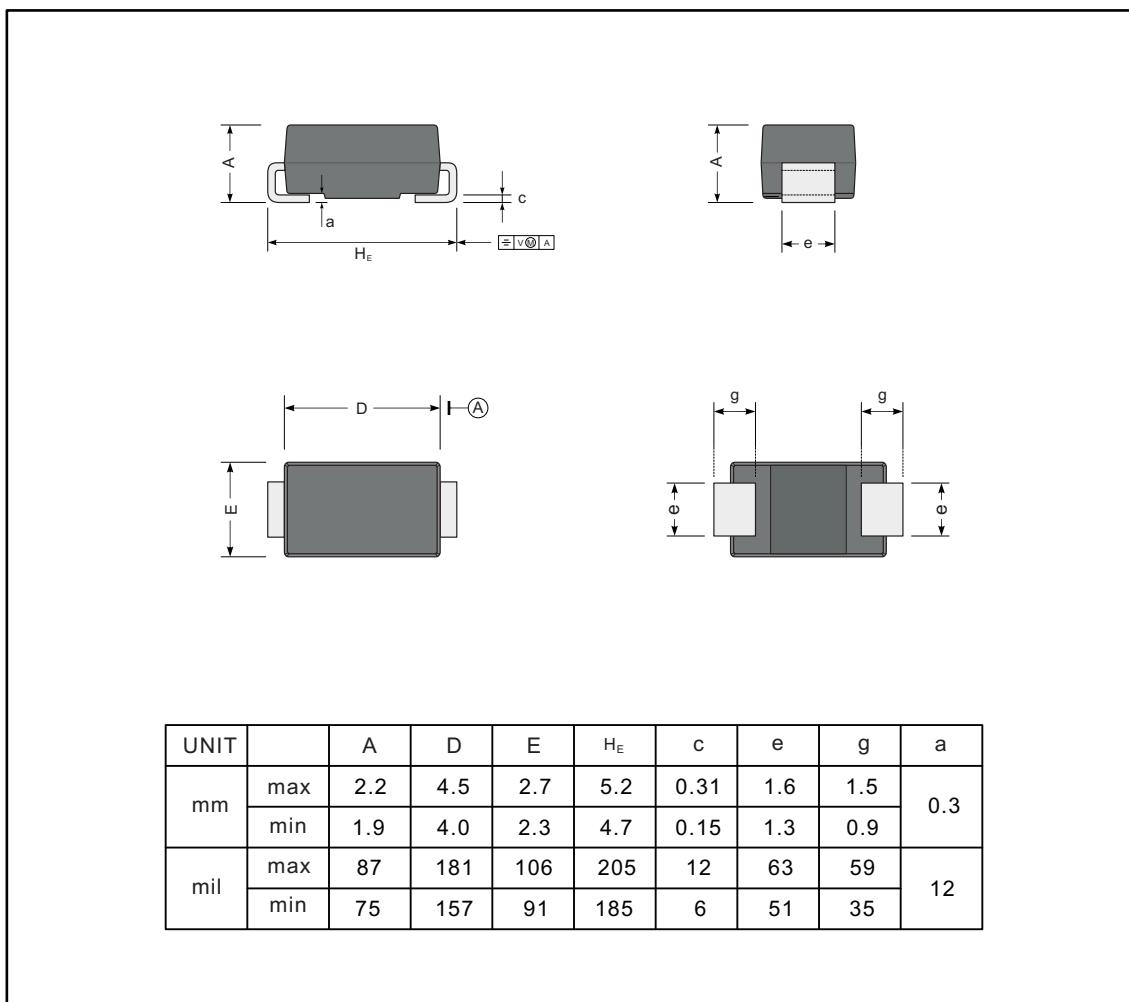
(2) P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**Fig.2 Maximum Average Forward Current Rating****Fig.4 Typical Forward Characteristics****Fig.6 Maximum Non-Repetitive Peak Forward Surge Current****Fig.3 Typical Reverse Characteristics****Fig.5 Typical Junction Capacitance**

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



The recommended mounting pad size

